

Notes: (Unless Otherwise Specified).

1) BODY: PLASTIC, SEMICONDUCTOR GRADE.

2) LEAD FRAME: COPPER, C-194 F/H.

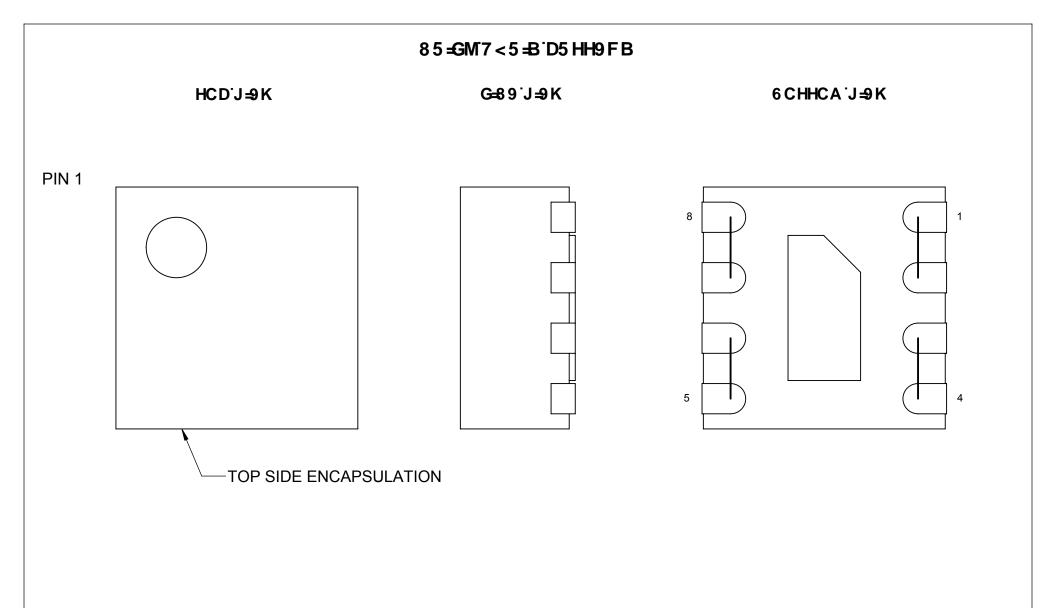
3) LEAD FRAME PLATING: NiPdAu.

4) FRAME THICKNESS: 0.203mm.

5) DIE PAD: 1.2 x 0.6mm EXPOSED BOTTOM.

6) JEDEC OUTLINE: MO-220. 7) DIMENSIONS IN mm.

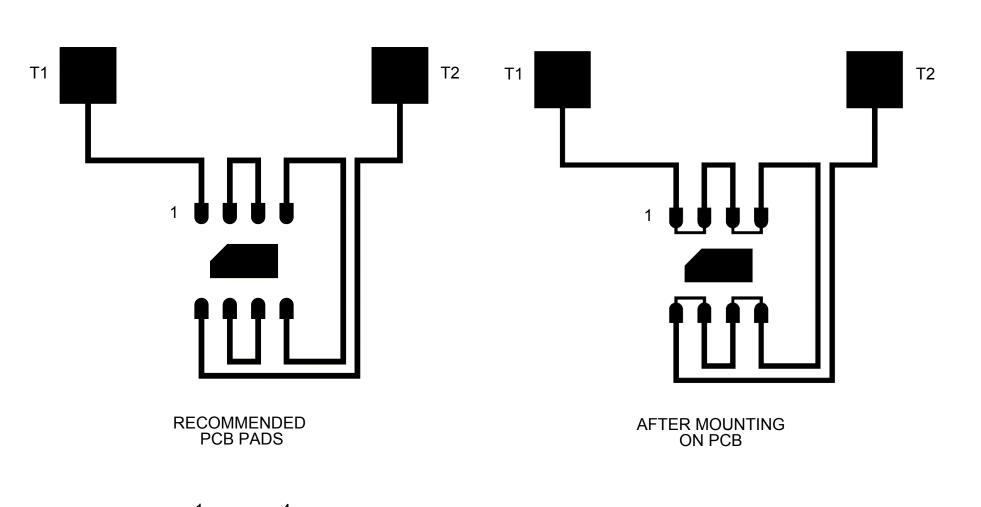
APPROVA	ALS	DATE	TopLine [®]				
DRAWN	T.Au	4/6/2020					
ENG	M. Hart	4/6/2020	TITLE 8-LEAD 2mm P0.5mm				
MFG			DFN DAISY CHAIN				
QA			SCALE SIZE DRAWING NO. REV				REV
CUST			15:1 A 450840 A				Α
REVISED			DO NOT SCALE DRAWING SHEET 1 OF 5			1 OF 5	



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1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

<u>TopLine</u> ®							
TITLE	TITLE 8-LEAD 2mm P0.5mm DFN DAISY CHAIN						
SCALE SIZE DRAWING NO. REV							
16:1 A 450840 A							
DO NOT SCALE DRAWING SHEET 2 OF 5							



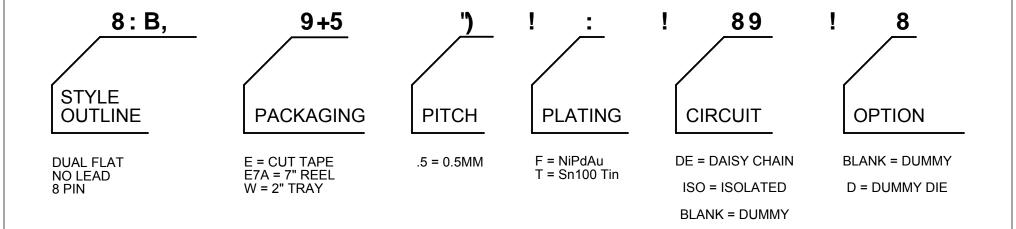
1	4	1
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8		5

DFN

85=GM7<5=B B9H"@-GH				
PINS	PINS			
1 ~ 2	3 ~ 4			
5 ~ 6	7 ~ 8			

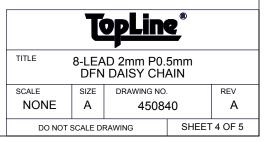
<u>TopLine</u> °						
TITLE	8-LEAD 2mm P0.5mm DFN DAISY CHAIN					
SCALE SIZE DRAWING NO. REV						
10:1	Α	450840 A				
DO NOT SCALE DRAWING			SHEET	3 OF 5		

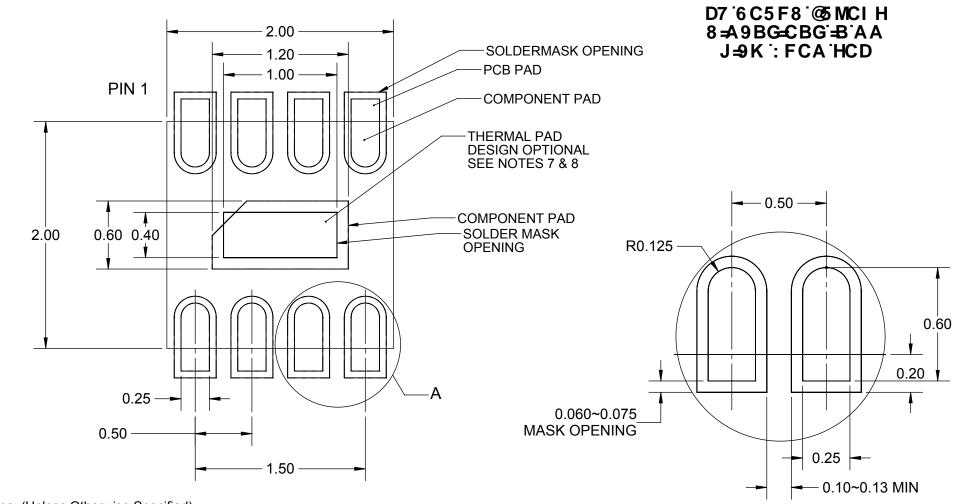
D5FHBI A69F=B; 'GMGH9A



D5FHBI A69F	85=GM 7<5=B	D57?5; =B;	Fc <g DV!: F99</g 	AG@ @9J9@	81 AAM 8 -9
DFN8E7A5-F-DE-D	YES	REEL	YES	1	YES
DFN8E.5-F-DE-D	YES	CUT TAPE	YES	1	YES
DFN8W.5-F-DE-D	YES	2" TRAY WAFFLE PACK	YES	1	YES

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.





Notes: (Unless Otherwise Specified).

1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.

DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.

- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
 - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
 - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERATURES INSTEAD OF ONE LARGE APERATURE TO CONTROL PASTE AMOUNTS.
 - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

DETAIL A SCALE 50 : 1

<u>TopLine</u> °						
8-LEAD 2mm P0.5mm DFN DAISY CHAIN						
SCALE SIZE DRAWING NO. REV						
18:1 A 450840 A						
DO NOT	SHEET	5 OF 5				